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# H1117J Series

1A LOW DROPOUT POSITIVE VOLTAGE REGULATOR

#### Features

- Low Dropout Voltage 1.2V at 1A
- Adjustable or Fixed Voltage
- Maximum Line Regulation 0.45%
- Maximum Load Regulation 0.4%
- Adjust Pin Current Less Than 90 uA
- Over Current Protection
- Thermal Protection

## **Applications**

- High Efficiency Linear Regulators
- 5V to 3.3V Voltage Converter
- Battery Charger

## **General Description**

The H1117J is a 1A low-dropout positive voltage regulator. It is available in fixed and adjustable output voltage versions. Over current and thermal protection are integrated onto the chip. Output current will decrease while it reaches the pre-set current or temperature limit. The dropout voltage is specified at 1.2V Maximum at full rated output current. H1117J Series provides excellent regulation over variations due to changes in line, load and temperature. H1117J is three terminal regulator and available in popular packages.

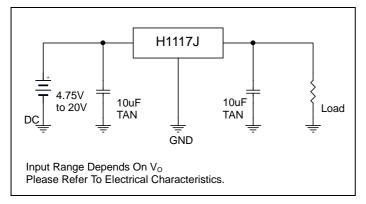
## **Device Selection Guide**

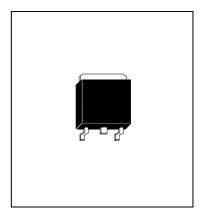
Device	Output Voltage	Package		
H1117J(Adj)	1.3V to 4V	D-PAK		
H1117-3.3J	3.3	TO-252		

## **Absolute Maximum Ratings**

Parameter	Symbol	Maximum	Units
Input Voltage	V <sub>IN</sub>	20	V
Power Dissipation	P <sub>D</sub>	Internally Limited	W
Thermal Resistance Junction To Case TO-252	$\theta_{JC}$	15	°C/W
Thermal Resistance Junction To Ambient TO-252	$\theta_{JA}$	156	°C/W
Operating Junction Temperature Range	Tj	0 To 125	°C
Storage Temperature Range	T <sub>STG</sub>	-65 To 150	°C
Lead Temperature (Soldering) 10 Sec	T <sub>LEAD</sub>	260	°C

## **Typical Application**

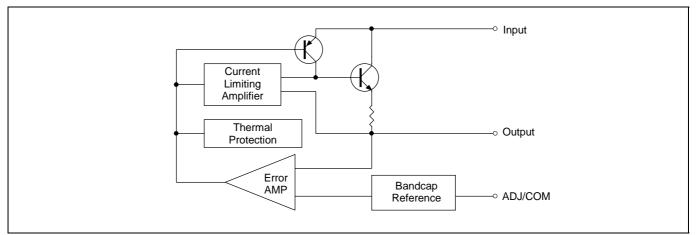






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## **Block Diagram**



## **Electrical Characteristics**

#### H1117J (adj version)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Units
Reference Voltage	$V_{REF}$	V <sub>IN</sub> =5V, I <sub>O</sub> =10mA, T <sub>i</sub> =25°C	1.238	1.25	1.262	V
Reference voltage		V <sub>IN</sub> =5V, I <sub>O</sub> =10mA, Over Temp.	1.225	1.25	1.275	
Line Regulation	Reg <sub>LINE</sub>	V <sub>IN</sub> =4.75~20V, I <sub>O</sub> =10mA, T <sub>i</sub> =25°C	-	-	0.3	%
		V <sub>IN</sub> =4.75~20V, I <sub>O</sub> =10mA, Over Temp.	-	-	0.45	/0
Load Regulation	Dee	V <sub>IN</sub> =5V, I <sub>O</sub> =10mA~1A,T <sub>i</sub> =25°C	-	0.05	0.3	%
	Reg <sub>LOAD</sub>	V <sub>IN</sub> =5V, I <sub>O</sub> =10mA~1A, Over Temp.	-	0.2	0.4	70
Dropout Voltage	VD	$I_0=10mA\sim1A$ , Over Temp., $\Delta V_0=\pm1\%$	-	1	1.2	V
Current Limit	I <sub>S</sub>	V <sub>IN</sub> =2.75~7V, Over Temp.	1	-	-	Α
Temperature Coeff.	T <sub>c</sub>	V <sub>IN</sub> =2.75~7V, I <sub>O</sub> =10mA~1A	-	0.005	-	%/°C
A divet Die Oversent	l <sub>adj</sub>	V <sub>IN</sub> =2.75~7V, I <sub>O</sub> =10mA~1A,Tj=25°C		55	-	
Adjust Pin Current		V <sub>IN</sub> =2.75~7V, I <sub>O</sub> =10mA~1A, Over Temp.	-	-	90	uA
Adjust Pin Current Change	$\Delta I_{adj}$	V <sub>IN</sub> =2.75~7V, I <sub>O</sub> =10mA~1A, Over Temp.	-	0.2	5	
Temperature Stability	Ts	V <sub>IN</sub> =5V, I <sub>O</sub> =100mA, Over Temp.	-	0.5	-	%
Minimum Load Current	l <sub>o</sub>	V <sub>IN</sub> =5V	-	5	10	mA
RMS Output Noise	V <sub>N</sub>	T <sub>i</sub> =25°C	-	0.003	-	%
Ripple Rejection Ratio	R <sub>A</sub>	V <sub>IN</sub> =5V, I <sub>O</sub> =1A, Over Temp.	60	72	-	dB

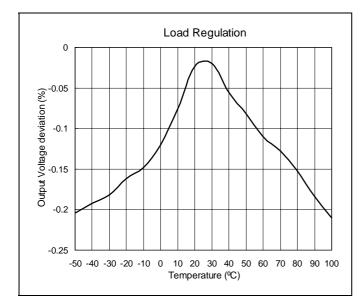
#### H1117-3.3J

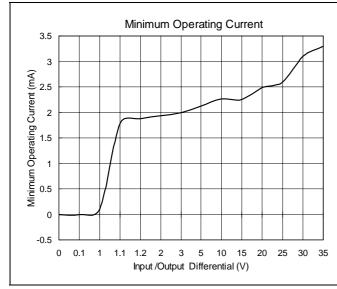
Parameter	Symbol	Test Conditions	Min	Тур	Max	Units
Output Voltage	Vo	V <sub>IN</sub> =5V, I <sub>O</sub> =0A,T <sub>i</sub> =25°C	3.270	3.3	3.333	V
Odiput voltage		V <sub>IN</sub> =5V, I <sub>O</sub> =0A, Over Temp.	3.234	3.3	3.366	v
Line Regulation	Dog	V <sub>IN</sub> =4.75~20V, I <sub>O</sub> =0A, T <sub>i</sub> =25°C	-	-	0.3	%
	Reg <sub>LINE</sub>	V <sub>IN</sub> =4.75~20V, I <sub>O</sub> =0A, Over Temp.	-	-	0.45	
Load Regulation	Reg <sub>LOAD</sub>	V <sub>IN</sub> =5V, I <sub>O</sub> =0A~1A,T <sub>i</sub> =25°C	-	0.05	0.3	%
		V <sub>IN</sub> =5V, I <sub>O</sub> =0A~1A, Over Temp.	-	0.2	0.4	70
Dropout Voltage	VD	I <sub>O</sub> =0A~1A, Over Temp., ∆V <sub>O</sub> =±1%	-	1	1.2	V
Current Limit	I <sub>S</sub>	V <sub>IN</sub> =4.75~7V, Over Temp.	1	-	-	Α
Quiescent Current	lq	V <sub>IN</sub> =5V, I <sub>O</sub> =0A~1A,Over Temp.	-	12	13	mA
Temperature Coeff.	T <sub>c</sub>	V <sub>IN</sub> =4.75~7V, I <sub>O</sub> =0A~1A	-	0.005	-	%/°C
Temperature Stability	Τs	V <sub>IN</sub> =5V, I <sub>O</sub> =100mA, Over Temp.	-	0.5	-	%
RMS Output Noise	V <sub>N</sub>	T <sub>i</sub> =25°C	-	0.003	-	%
Ripple Rejection Ratio	R <sub>A</sub>	V <sub>IN</sub> =5V, I <sub>O</sub> =1A, Over Temp.	60	72	-	dB

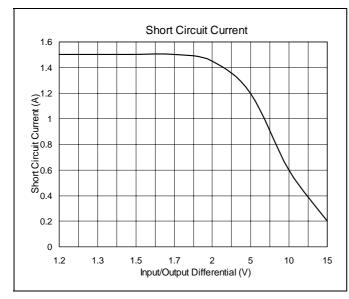


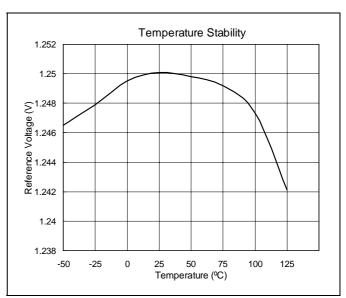
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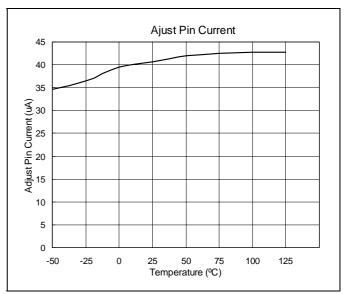
## **Characteristics Curve**

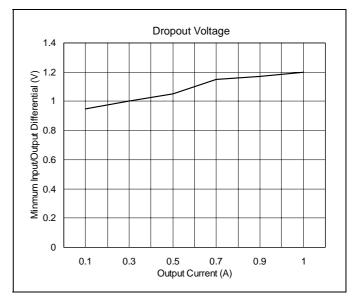














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## **Applications Description**

#### Output Voltage Adjustment

Like most regulators, the H1117J regulates the output by comparing the output voltage to an internally generated reference voltage. On the adjustable version, the V<sub>REF</sub> is available externally as 1.25V between V<sub>OUT</sub> and ADJ. The voltage ratio formed by R<sub>1</sub> and R<sub>2</sub> should be set to conduct 10mA (minimum output load). The output voltage is given by the following equation : V<sub>OUT</sub> =V<sub>REF</sub> (1+R<sub>2</sub>/R<sub>1</sub>) + I<sub>ADJ</sub> R<sub>2</sub> On fixed versions of H1117J, the voltage divider is provided internally.

#### Thermal Protection

H1117J has thermal protection which limits junction temperature to  $150^{\circ}$ C. However, device functionality is only guaranteed to a maximum junction temperature of +125°C.

The power dissipation and junction temperature for H1117J in TO-252 package given by  $P_D=(V_{IN} - V_{OUT}) I_{OUT}, T_{JUNCTION}=T_{AMBIENT}+(P_D x \theta_{JA})$ , Note :  $T_{JUNCTION}$  must not exceed 125°C

#### • Current Limit Protection

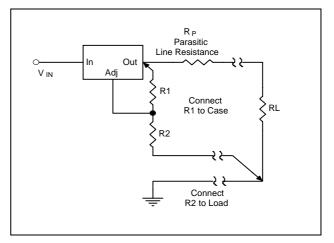
H1117J is protected against overload conditions. Current protection is triggered at typically 1.5A.

#### Stability And Load Regulation

H1117J requires a capacitor from V<sub>OUT</sub> to GND to provide compensation feedback to the internal gain stage. This is to ensure stability at the output terminal. Typically, a 10uF tantalum or 50uF aluminum electrolytic is sufficient. Note : It is important that the ESR for this capacitor does not exceed  $0.5\Omega$ .

The output capacitor does not have a theoretical upper limit and increasing its value will increase stability.  $C_{OUT} = 100 \text{ uF}$  or more is typical for high current regulator design.

H1117J load regulation is limited by the resistance of the wire connecting it to the load( $R_P$ ). For the adjustable version, the best load regulation is accomplished when the top of the resistor divider( $R_1$ ) is connected directly to the output pin of the H1117J. When so connected,  $R_P$  is not multiplied by the divider ratio. For fixed output versions,

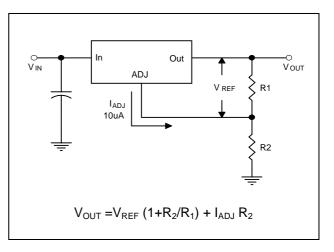


the top of  $R_1$  is internally connected to the output and ground pin can be connected to low side of the load as a negative side sense if, so desired.

#### • Thermal Consideration

The H1117J series contain thermal limiting circuitry designed to protect itself for over-temperature conditions. Even for normal load conditions, maximum junction temperature ratings must not be exceeded. As mention in thermal protection section, we need to consider all sources of thermal resistance between junction and ambient. It contains junction-to-case, case-to-heat-sink interface and heat sink resistance itself. An additional heat sink is applied externally sometimes. It can increase the maximum power dissipation. For example, the equivalent junction temperature of 300mA output current is 115°C without external heat sink. Under the same junction temperature IC can operates 500mA with an adequate heat sink. Therefore, to attach an extra heat sink is recommended.

Junction-to-case thermal resistance is specified from the IC junction to the bottom of the case directly below the die. The bonding wires are appending paths. The former is the lowest resistance path. Proper mounting is required to ensure the best possible thermal flow this area of the package to the heat sink. Thermal compound at the case-to-heat-sink interface is strongly recommended. The case of all devices in this series is electrically connected to the output. Therefore, if the case of the device must be electrically isolated, a thermally conductive spacer can be used, as long its thermal resistance is considered.





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#### Protection Diode

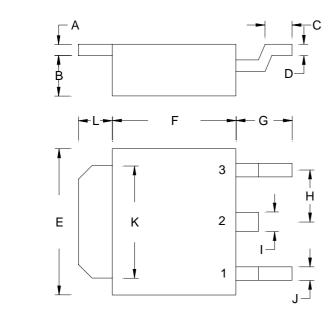
(The figure is shown as Regulator with Reverse Diode Protection in advanced applications)

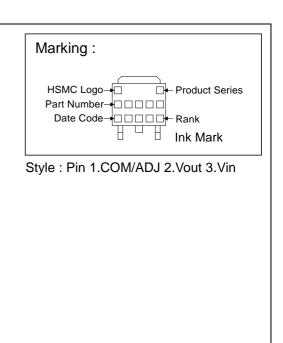
In general operation, H1117J does not need any protection diodes. From the cross-section structure of H1117J, the output pin is connected to P+ substrate, and the input pin is connected to N- well. There is a parasitic reverse diode between them. It can handle microsecond surge currents of 5A to 10A. Even with large output capacitance, it is very difficult to get those values of surge currents in normal operation. Only with high value output capacitors, such as 1000uF. And with the input pin instantaneously shorted to ground. can damage occur. A crowbar circuit at the input of the H1117J can generate those kinds of currents, and a diode from output to input is recommended. Normal power supply cycling or even plugging and unplugging in the system will not generate currents large enough to do any damage.



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## **TO-252** Dimension





3-Lead TO-252 Plastic Surface Mount Package HSMC Package Code : J

*:Typical									
DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
Α	0.0177	0.0217	0.45	0.55	G	0.0866	0.1102	2.20	2.80
В	0.0650	0.0768	1.65	1.95	H	-	*0.0906	-	*2.30
С	0.0354	0.0591	0.90	1.50		-	0.0354	-	0.90
D	0.0177	0.0236	0.45	0.60	J	-	0.0315	-	0.80
E	0.2520	0.2677	6.40	6.80	K	0.2047	0.2165	5.20	5.50
F	0.2125	0.2283	5.40	5.80	L	0.0551	0.0630	1.40	1.60

Notes: 1.Dimension and tolerance based on our Spec. dated May. 05,1996.

2.Controlling dimension : millimeters.

3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material. 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

• Lead : 42 Alloy ; solder plating

• Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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